



Material Content Data Sheet



Sales Product Name		XMC1302-T028X0128 AB		Issued		1. August 2018		
MA#		MA001798360						
Package		PG-TSSOP-28-16		Weight*		105.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.226	1.16	1.16	11567	11567
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		96	
	non noble metal	zinc	7440-66-6	0.041	0.04		385	
	non noble metal	iron	7439-89-6	0.815	0.77		7694	
wire	non noble metal	copper	7440-50-8	33.103	31.24	32.06	312397	320572
	noble metal	palladium	7440-05-3	0.002	0.00		18	
encapsulation	non noble metal	copper	7440-50-8	0.189	0.18	0.18	1782	1800
	organic material	carbon black	1333-86-4	0.203	0.19		1914	
	plastics	epoxy resin	-	7.908	7.46		74634	
leadfinish	inorganic material	silicondioxide	60676-86-0	59.483	56.14	63.79	561348	637896
	non noble metal	tin	7440-31-5	1.539	1.45	1.45	14528	14528
plating	noble metal	silver	7440-22-4	1.002	0.95	0.95	9454	9454
glue	plastics	epoxy resin	-	0.111	0.10		1046	
	noble metal	silver	7440-22-4	0.332	0.31	0.41	3137	4183
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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